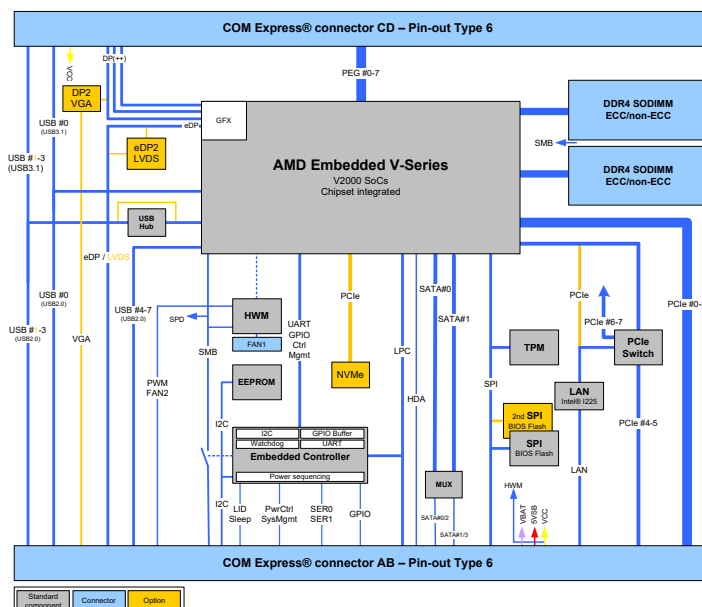


COM Express® Basic Type 6 with AMD Ryzen™ Embedded V-Series V2000 SoCs

- ▶ Up to 64 GByte DDR4 memory
- ▶ Up to 2.5 Gb Ethernet
- ▶ Optional NVMe SSD onboard

COMPLIANCE	COM Express® basic Pin-out type 6
DIMENSIONS (H X W X D)	95 x 125 mm
CPU	AMD Ryzen™ Embedded V-Series V2000 SoCs: AMD V2748, 8x 2.9 GHz, 35-54 W AMD V2718, 8x 1.7 GHz, 12-25 W AMD V2546, 6x 3.0 GHz, 35-54 W AMD V2516, 6x2.1 GHz, 12-25 W
CHIPSET	Integrated SoC
MAIN MEMORY	2x DDR4 SO-DIMM with up to 32 GByte per channel (non-ECC/ECC)
GRAPHICS CONTROLLER	AMD Radeon™ GPU
ETHERNET CONTROLLER	Intel® i225
ETHERNET	Up to 2.5 Gb Ethernet
STORAGE	2x SATA 6Gb/s
FLASH ONBOARD	Up to 1 TByte NVMe SSD (on request)
PCI EXPRESS®	4x PCIe 3.0 (up to 8 GT/s) 4x PCIe 2.0 (up to 5 GT/s) via PCIe switch 1x PEG x8
DISPLAY	DDI1: DP++, DDI2: DP++, DDI3: DP++, VGA: -, eDP
USB	4x USB 3.1 (incl. USB 2.0) + 4x USB 2.0
SERIAL	2x serial interface (RX/TX only)
AUDIO	High Definition Audio interface
OTHER FEATURES	SPI, LPC, SMB, Fast I ² C, Staged Watchdog, RTC
SPECIAL FEATURES	POSCAP capacitors, Trusted Platform Module TPM 2.0
FEATURES ON REQUEST	LVDS (Dual Channel 18/24bit) instead of eDP, VGA, NVMe SSD, Fail Safe via 2nd SPI Flash, Industrial grade -40 °C to +85 °C
POWER MANAGEMENT	ACPI 6.0
POWER SUPPLY	8.5 V – 20 V Wide Range, Single Supply Power
BIOS	AMI Aptio V
OPERATING SYSTEM	Windows®10, Linux
TEMPERATURE	Commercial temperature: 0 °C to +60 °C operating, -30 °C to +85 °C non-operating Extended temperature: -25 °C to +75 °C operating, -30 °C to +85 °C non-operating
HUMIDITY	93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78)

Block Diagram



CPU	V2748	V2718	V2546	V2516
CORES	8	8	6	6
FREQUENCY BASE/TURBO	2.9/4.25 GHz	1.7/4.15 GHz	3/3.95 GHz	2.10/3.95 GHz
TDP	35/54 W	12/25 W	35/54 W	12/25 W
CACHE	4 MByte	4 MByte	3 MByte	3 MByte

Variants

PART NO.	CPU	PCH	MEM. DOWN	SO-DIMM	FLASH	OP. TEMPERATURE
38036-0000-29-8 *	V2748	integrated	-	non-ECC/ECC	-	0 °C - 60 °C
38036-0000-17-8 *	V2718	integrated	-	non-ECC/ECC	-	0 °C - 60 °C
38036-0000-30-6 *	V2546	integrated	-	non-ECC/ECC	-	0 °C - 60 °C
38036-0000-21-6 *	V2516	integrated	-	non-ECC/ECC	-	0 °C - 60 °C

* Qualified for E1 temperature range (-25 °C to +75 °C) and available project based only

Carrier

ARTICLE	PART NO.	DESCRIPTION
COME EVAL CARRIER2 T6	38116-0000-00-5	COM Express® Evaluation Carrier Type 6

ARTICLE	PART NO.	DESCRIPTION
HSP COME-BV26 CU-CORE THREADED	38036-0000-99-0	Heatspreader for COMe-bV26, Cu-core, threaded mounting holes
HSP COME-BV26 CU-CORE THROUGH	38036-0000-99-1	Heatspreader for COMe-bV26, Cu-core, through mounting holes
HSK COME-BASIC ACTIVE (W/O HSP)	38025-0000-99-0C05	Active Cooler for COMe-bxL6/bDV7 to be mounted on HSP
HSK COME-BASIC PASSIVE (W/O HSP)	38025-0000-99-0C06	Passive Cooler for COMe-bxL6/bDV7 to be mounted on HSP

Memory

PART NO.	MIN. SPEC.	SIZE	ECC	OP. TEMPERATURE
97020-3232-BV26	DDR4-3200	32 GByte	no	0 °C - 60 °C
97020-1632-BV26	DDR4-3200	16 GByte	no	0 °C - 60 °C
97020-0832-BV26	DDR4-3200	8 GByte	no	0 °C - 60 °C
97020-0432-BV26	DDR4-3200	4 GByte	no	0 °C - 60 °C
97030-3232-BV26	DDR4-3200	32 GByte	yes	0 °C - 60 °C
97030-1632-BV26	DDR4-3200	16 GByte	yes	0 °C - 60 °C
97030-0832-BV26	DDR4-3200	8 GByte	yes	0 °C - 60 °C
97030-0432-BV26	DDR4-3200	4 GByte	yes	0 °C - 60 °C
97021-3232-BV26*	DDR4-3200	32 GByte	no	-40 °C - 85 °C
97021-1632-BV26*	DDR4-3200	16 GByte	no	-40 °C - 85 °C
97021-0832-BV26*	DDR4-3200	8 GByte	no	-40 °C - 85 °C
97021-0432-BV26*	DDR4-3200	4 GByte	no	-40 °C - 85 °C

* Corresponding memory modules in case of project based E1 temperature range variants

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